

Bill of Materials

	SCK1	SK3	Remarks
Core Material	Kinsus/Samsung BT/HL-832	Kinsus/Samsung BT/HL-832	Same BOM
Die Attach	Ablestik 2025D (bottom die) Loctite/Hysol QMI536 (spacer) Ablestik 2025M (top die) Ablestik 2000 (Die Attach) Hereaus 96.5Sn/3.5Ag (Discrete Component Attach) Ablestik ATB225 (bottom die) Ablestik ATB120 (spacer) Ablestik ATB120 (top die)	Ablestik 2025D (bottom die) Loctite/Hysol QMI536 (spacer) Ablestik 2025M (top die) Ablestik 2000 (Die Attach) Hereaus 96.5Sn/3.5Ag (Discrete Component Attach) Ablestik ATB225 (bottom die) Ablestik ATB120 (spacer) Ablestik ATB120 (top die)	
Wire type	Gold MKE R 2N	Gold MKE R 2N	
Mold Compound	Sumitomo EME-G770LC Sumitomo EME-G760C Sumitomo EME-G760SYA	Sumitomo EME-G770LC Sumitomo EME-G760C Sumitomo EME-G760SYA	
Lead Finish	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu	

Bill of Materials (continuation)

	SCK1	SK3	Remarks
Core Material	BT/HL-832 DS-7409HGB	BT/HL-832 DS-7409HGB	Same BOM
Chip Bump Composition	96.5Sn_3.0Ag_0.5Cu 97.5Sn_2.5Ag 98.2Sn_1.8Ag	96.5Sn_3.0Ag_0.5Cu 97.5Sn_2.5Ag 98.2Sn_1.8Ag	
Heat Spreader Material	C1100 Cu_Ni plated	C1100 Cu_Ni plated	
Heat Spreader Attach Material	Momentive TSE-3280G Hysol QMI 529HT	Momentive TSE-3280G Hysol QMI 529HT	
Underfill Material	Namics U8410-73C	Namics U8410-73C	
Terminal Finish Composition	62.0Sn_36.0Pb_2.0Ag 96.5Sn_3.0Ag_0.5Cu	62.0Sn_36.0Pb_2.0Ag 96.5Sn_3.0Ag_0.5Cu	
Thermal Interface Material	Dow Corning SE4450	Dow Corning SE4450	